



HIGH-FLEX™ BLACK CONDUCTIVE FABRIC TAPES

Laird's High-Flex™ Black Conductive Fabric Tapes offer exceptional conformability and conductivity for dynamic flex applications. Each tape is constructed of black colored nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions.

Laird offers several thicknesses for selection. All the tapes are halogen free product and can be supplied in tape or further customized to application by die-cutting or hole punching.

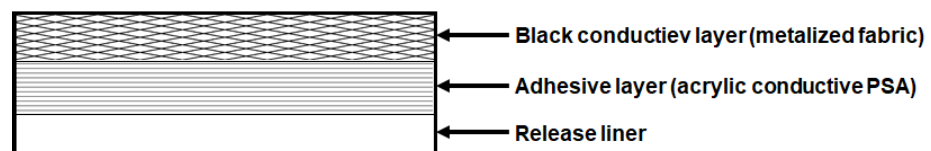
FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity provides excellent conductivity
- Shielding effectiveness of >60 dB across a wide spectrum of frequencies

APPLICATIONS

- Cabinet applications
- Displays
- Medical equipment
- Servers
- Desktop/laptop computers
- Telecommunications cabinets

COMPOSITION



CHARACTERISTICS

ITEM	UNIT	Value						TEST METHOD
		85203	86205	86285	86250	96249J	96249	
Thickness	mm	0.13	0.13	0.12	0.080	0.10	0.053	-
Peel Adhesion	Kgf/25 mm	>1.0	>1.1	>1.0	>1.2	>1.0	>0.8	PSTC 101*
Shear Adhesion at R.T.	Hrs	>168	>168	>168	>24	>24	>24	PSTC 107#
Tensile Strength	Kgf/25 mm	>15	>12	>12	>7	>6	>6	-
Operation Temperature	°C	-40 - 85	-40 - 85	-40 - 85	-40 - 85	-40 - 85	-40 - 85	-
Surface Resistivity (Fabric Side)	Ω/□	<0.06	<0.06	<0.06	<0.06	<0.10	<0.10	ASTM F390
Z-axial Resistance	Ω	<0.04	<0.04	<0.04	<0.04	<0.10	<0.10	-
Shielding Effectiveness+								ASTM D4935
at 100 MHz	dB	82	73	75	68	60	60	
at 1GHz	dB	78	78	80	73	67	67	
Package Dimensions (Max. Width: 1000 mm)		Width: customized, max. width 1000 mm Length : standard length 20 M.						-
Shelf Life		12 months under 23°C/65% R.H.						-

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

LAIRD PERFORMANCE MATERIALS

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APPLICATION TECHNIQUES

- Adhesion is dependent upon the amount of adhesive-to-surface contact developed. Apply normal pressure to the bonding surface will develop better adhesive contact, and thus improve adhesion.
To a 25mm(1in.) width tape, recommend to use a 2Kgf rubber roller to press back and forth twice under the speed of 5mm/sec. Users may adjust the speed or roller loading according to different application.
Users may also apply 5psi for 10sec to the surface. The loading and residual time can be adjusted as well according to the application and area.
- After applying the tape onto a surface, the adhesion will go up gradually.
- To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
- Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.

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